

DIE BONDER

T-3000-FC3

The **T-3000-FC3** series is Tresky's most flexible die bonding platform. The systems can run all basic functions as well as the industries most advanced applications by adding a wide range of available options. As with all of Tresky's products, the FC3 incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Together with superior ergonomics the FC3 platform is the industry's most sophisticated system in its class.

True Vertical Technology™

Ultra precise bond-height control

Multi functional software

Up to 500N Bond-Force

MICRO ASSEMBLY

T-3000-FC3



TRESKY

Dr. TRESKY AG

Switzerland

Email: tresky@tresky.com

www.tresky.com

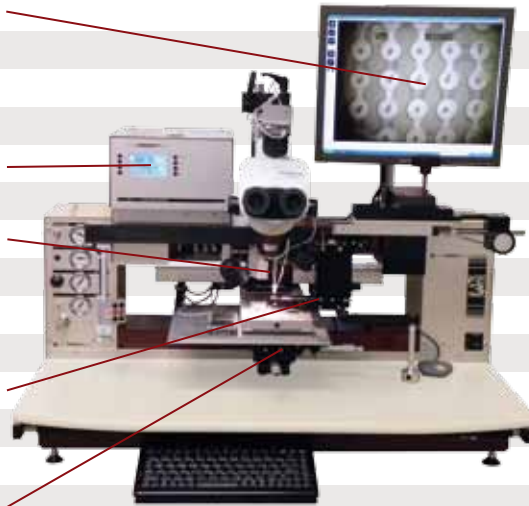
Advanced multi functional die bonder with superior ergonomic design and programmable, high accuracy Z-Drive and bond-force control.

APPLICATIONS:

Die Attach, Flip-Chip, Thermocompression, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermo-sonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu,),

FEATURES AND OPTIONS:

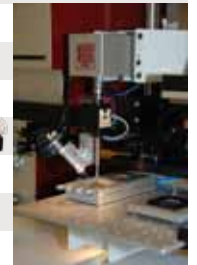
- Interface for temperature profile and video imaging
 - > HD Image of Beam Splitter Optics
 - > Process Inspection Camera
- Programmable Z-Drive with Bond-Force Control
- TRUE VERTICAL TECHNOLOGY™ Z-movement 95mm with 360° tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre-Form Spindle, ...
- Flip-Chip09mpa Beam Splitter with multi point alignment
 - > 1µm placement accuracy
- XY placement stage with micrometer screws supporting:
Waffle- / Gel- Pack -, Substrate Holder, various Heating Plates



Low Bond Force



High Bond Force



TECHNICAL DATA:

XY- Movement (placement stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360°
Bond Force (standard range):	20g - 400g; Optional up to 50Kg
Bond Force (repeatability):	±1g
Z-Measurement resolution:	±0.001mm
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	10µm; 1µm with high accuracy beam splitter (Flip-Chip09mpa)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

REPRESENTED BY:

HEADQUARTERS

Dr. TRESKY AG
Boehnirainstr. 13
CH-8800 Thalwil
Switzerland
Tel.: +41 44 772 1941
Fax: +41 44 772 1945
tresky@tresky.com

TRESKY Competence Center
Lange Enden 29
D-13437 Berlin
Germany
Tel.: +49 30 683 208 92
Fax: +49 30 683 208 94
daniel.schultze@tresky.com

TRESKY Corporation
704 Ginesi Drive, Suite 11A
Morganville, NJ 07751
USA
Tel.: +1 732 536 8600
Fax: +1 732 536 0495
sales@tresky.com

www.tresky.com

